

Product Change Notification

Product Change Notification Number: PDF-032

Notification Date: August 01, 2017

Title: Manufacturing Capacity Expansion for the 8-contact, 6 x 8mm, Very Thin Dual Flat No Lead Package (VDFN)			
Product Identification: Specific Adesto products offered in the 6x8 mm VDFN package (part number package suffix 'MW'). See Table I for a complete list of affected Adesto part numbers.			
Reason For Change	☒ Capacity Expansion	☒ Design	☒ Manufacturing Location
	☐ Material / Composition	☐ Processing/Manufacturing	☐ Quality & Reliability
Change Description: Addition of a qualified subcontractor for assembly and final electrical test services for products offered in the VDFN 6x8 mm package selection to further expand capacity. <i>NO external package dimensional changes, that would affect PCB board layout or device functionality, occur with this change (see Figure 1 for package thermal pad dimensions).</i>			
Quantifiable Impact on Quality & Reliability: No change in Quality or Reliability Affected products remain Form, Fit and Functionally compatible with the same products assembled in existing facilities. There is no impact on product availability or pricing			
Facility and Location:		Greatek Zhunan, Taiwan	
Certification:		ISO 9001, ISO/TS16949 & ISO 14001	
Affected Products:		See Table I of this Notice	
Last Time Buy: ☒ Not Applicable ☐ Applicable			
Implementation Date: See Table I			
Identification: ☐ Date Code ☒ Assembly ID Part Marking (backside) ☐ Ordering Part Number			
Qualification Report: ☐ Available Now ☒ See Table I for availability ☐ Not Applicable <i>Request the qualification report at pcn@adestotech.com</i>			
Product Samples: ☐ Available Now ☒ See Table I for availability ☐ Not Applicable <i>To order samples, message pcn@adestotech.com or contact an authorized distributor or Adesto manufacturing Representative.</i>			
CUSTOMER ACKNOWLEDGEMENT OF RECEIPT: Adesto requests your acknowledgement of the receipt of this Notice. Please email to PCN@adestotech.com to grant approval or request additional information. Adesto will deem this change accepted unless specific conditions of acceptance are received via an email addressed to PCN@adestotech.com within 30 days from the date of this notice.			

FIGURE 1 PACKAGE DIMENSIONAL CHANGES (published datasheet updated)

NO critical external package dimensional changes.

The minimum dimensions of the thermal pad have reduced as shown below.

Impact to board layout: NONE

These changes have no impact on board layout due to industry standard recommendation not to run PCB traces under the pad area.

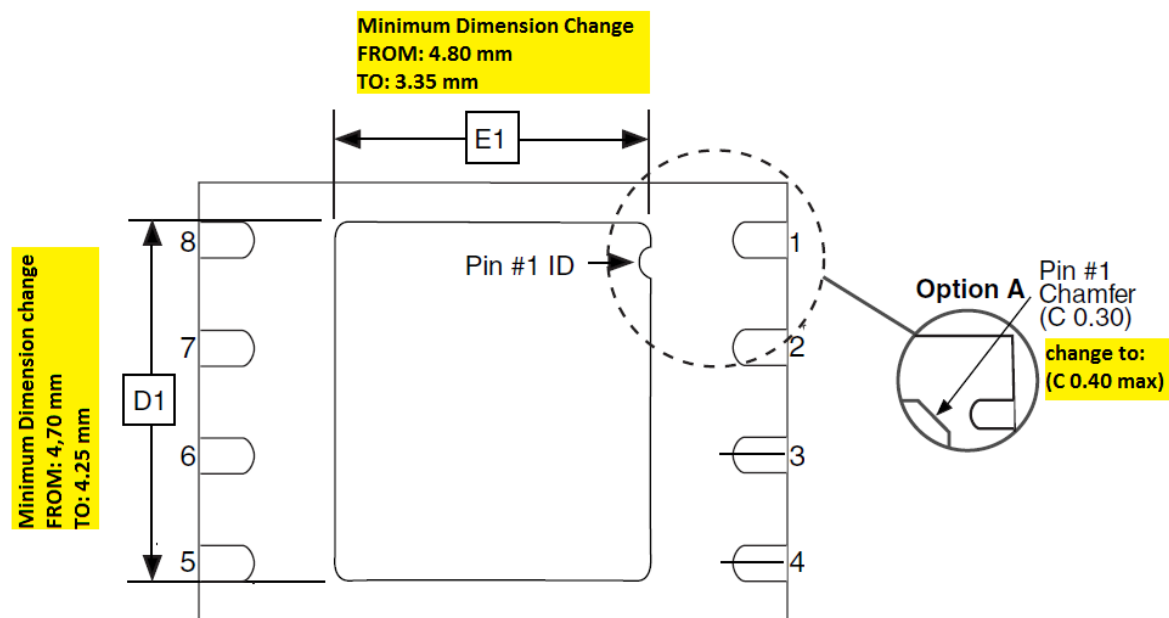


Table 1: Affected Part Numbers

Datasheet Part Number	Samples Available	Qualification Report Available	Production Implementation Date
AT45DB321E-MWHF-Y	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB321E-MWHF-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB321E-MWHF2B-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHF-Y	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHF-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHF2B-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHFHJ-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHFHK-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB641E-MWHN-Y	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB641E-MWHN-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB641E-MWHN2B-T	Sep 30, 2017	October 1, 2017	December 1, 2017